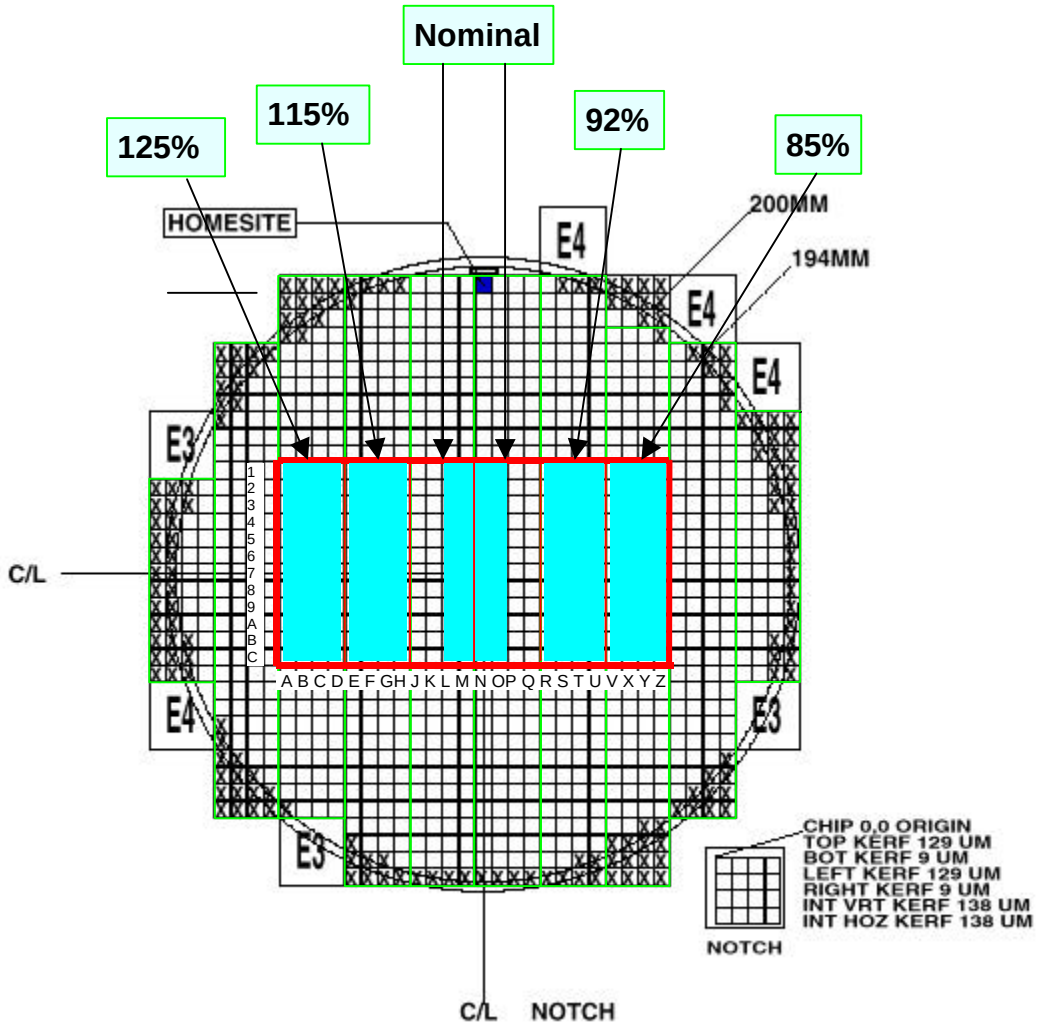
Wafer Serializing map



The wafer manufacturer of our DTMROC chip has manufactured a special wafer with five process corners. Since there are more than 1000 die on the 8" wafer we have chosen to concentrate our request for serialization of the packaged die in the shaded areas. We suggest a serialization that would result in an alpha-numeric location system for the240 die in the shaded areas. Serialization is optional of the four unshaded columns within the red rectangle.

Upper left corner	Die #1A	(row, column)
Lower left corner	Die #CA	
Upper Right corner	Die #1Z	
Lower Right corner	Die #CZ	

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Additional Packaging Details:

Number of Wafers: 1
Wafer Size 8”, 350µm thick
Total number of useable die = 1017 per wafer

Die size 5.2 X 5mm

Package type: 100Lead TQFP 14X14X1.4mm

Chip Label:

Serialized Chips	Normal Chips
DSM DTMROC # # Mar ‘02	DSM DTMROC Mar ‘02

is serialization number

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